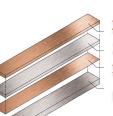


Objective O7.3: Optimize state-of-the-art electrochemical techniques for Nb3Sn thin layer deposition on Nb and on Cu

APPROACH I Electrodeposition + annealing

Electrdoeposition of **Cu/Sn/Cu multilayers** from aqueous solutions onto **Nb + Thermal treatment** for Sn-Nb interdiffusion



- 3. Copper barrier
- 2. Sn
- 1. Copper strike

Nb substrate

Copper barrier

- ✓ Prevents Sn leakage during TT
- ✓ Compact structure of samples



Copper strike gives

- ✓ Lower Nb3Sn formation T
- ✓ Higher grain boundary density
- ✓ Good adhesion
- ✓ Higher growth rate

APPROACH II Direct electrodeposition

Electrodeposition of Nb-Sn alloys onto Cu substrates

IONIC LIQUIDS

- EMIM: 1-Ethyl-3methylimidazolium chloride
- **BMIM**: 1-Butyl-3- methylimidazolium chloride





Work Package 7 - Advanced superconducting techniques for particle accelerators

Objective O7.3: Optimize state-of-the-art electrochemical techniques for Nb3Sn thin layer deposition on Nb and on Cu

State of the art at Polimi

I. 2012 Master thesis

Electrochemical synthesis of Nb-Sn coatings for High Field Accelerator Magnets (Federico Reginato)



US Patent "Synthesis of superconducting Nb-Sn" (Polimi, FermiLab)

II. 2014 Master thesis

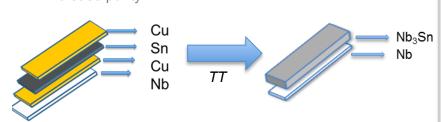
Electrochemical Synthesis of Nb-Sn Coatings from ionic liquids (Luigia Glionna)



Previous results were not reproduced

Activities mentioned in O7.3

- 1. Improve adhesion of the film
- 2. Optimize thermal treatments
- Achieve the best uniformity of the deposit across both flat and curved surfaces
- 4. Increase purity



Activities planned (months 3-21)

- a. Update of state of the art on Nb-Sn coatings obtained by electrodeposition
- b. Reproduce previous results with respect to:
 - a. Optimization of etching procedure to achieve good adhesion to the Nb substrate
 - b. Avoid corrosion problems
 - c. Avoid undesired barrier diffusion layers during thermal treatment
 - d. Optimization of thermal treatment of Cu/Sn/Cu multilayers onto Nb substrate



Objective O7.3: Optimize state of the art on electrochemical techniques (US patent pending) for Nb 3 Sn thin layer deposition on superconducting Nb and/or conventional Cu.

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35	ER	POLIMI	IT	40	1	
36	ER	POLIMI	IT	14	1	
36	ER	POLIMI	IT	32	1	
37	ESR	POLIMI	IT	14	1	
37	ESR	POLIMI	IT	15	1	
37	ESR	POLIMI	IT	26	1	
37	ESR	POLIMI	IT	27	1	
37	ESR	POLIMI	IT	42	1	
37	ESR	POLIMI	IT	43	1	